

1. Scope :

This specification applies to N/P/N silicon zener double diodes chips,
Device NO. SD-00617G

2. Structure :

- 2-1. Planar type : N/P/N.
- 2-2. Electrodes :
Top side : Gold pad.
Back side : Gold layer.

3. Size :

- 3-1. ^{**1} Chip size : 6.88 mils x 6.88 mils (0.175 mm x 0.175 mm).
- 3-2. Chip thickness : 4.72 ± 0.79 mils (0.120 ± 0.020 mm)
- 3-3. ^{**2} Bonding pad : 4.3 mils x 4.3 mils (0.110 mm x 0.110 mm).
- 3-4. Pattern drawing : Refer to the attached drawing.
^{**1} Including scribing line. The chip size is about (0.150±0.015)²mm² after dicing.
^{**2} The wire bonding pad dimension is (0.110±0.005)²mm².

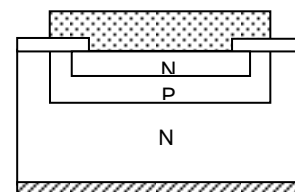
4. Electrical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Leakage Current	Idf	V=4V Ee=0mW/cm ²			100	nA
	Idr	V=11V Ee=0mW/cm ²			100	
Zener Voltage	Vz(forward)	Izf=10mA Ee=0mW/cm ²	6.0		8.0	V
	Vz(reverse)	Izr=10mA Ee=0mW/cm ²	13		19.5	



5. Annotation :

- 5-1. Parallel with one LED
- 5-2. Single pad (one wire bonding applied only)
- 5-3. Double direction Zener diode protection



Equivalent Circuit

